## 2SC2816

## Silicon NPN Triple Diffused

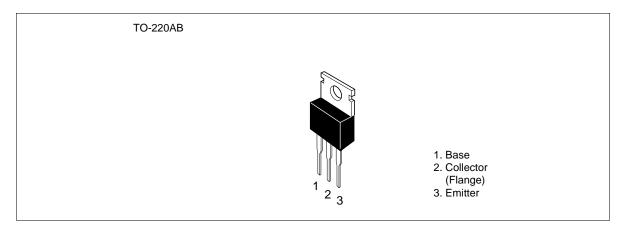
## **HITACHI**

ADE-208-887 (Z) 1st. Edition Sep. 2000

#### **Application**

High voltage, high speed and high power switching

#### **Outline**



### **Absolute Maximum Ratings** $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	500	V
Collector to emitter voltage	V <sub>CEO</sub>	400	V
Emitter to base voltage	$V_{EBO}$	7	V
Collector current	I <sub>c</sub>	5	A
Collector peak current	I <sub>C(peak)</sub>	10	A
Base current	I <sub>B</sub>	2.5	А
Collector power dissipation	P <sub>c</sub> *1	40	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Value at  $T_c = 25^{\circ}C$ .

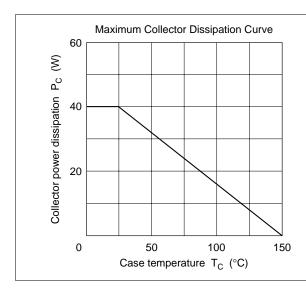


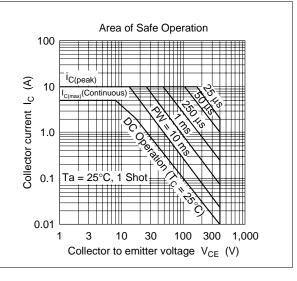
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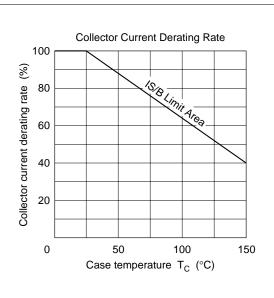
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

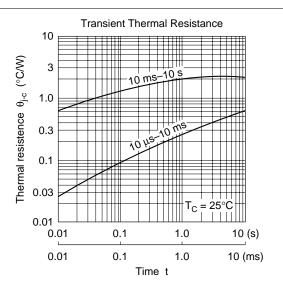
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter sustain voltage	$V_{\text{CEO(sus)}}$	400	_	_	V	$I_{c} = 0.2 \text{ A}, R_{BE} = \infty, L = 100 \text{ mH}$
	V <sub>CEX(sus)</sub>	400	_	_	V	$I_C = 5 \text{ A}, I_{B1} = -I_{B2} = 1.0 \text{ A}$ $V_{BE} = -5.0 \text{ V}, L = 180 \mu\text{H},$ Clamped
Emitter to base breakdown voltage	$V_{(BR)EBO}$	7	_	_	V	$I_{E} = 10 \text{ mA}, I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>		_	50	μΑ	$V_{CB} = 400 \text{ V}, I_{E} = 0$
	$I_{\text{CEO}}$	_	_	50	μΑ	$V_{CE} = 350 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h <sub>FE1</sub>	15	_	_		$V_{CE} = 5.0 \text{ V}, I_{C} = 2.5 \text{ A}^{*1}$
	$h_{\text{FE2}}$	7	_	_		$V_{CE} = 5.0 \text{ V}, I_{C} = 5 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	1.0	V	$I_{\rm C} = 2.5 \text{ A}, I_{\rm B} = 0.5 \text{ A}^{*1}$
Base to emitter saturation voltage	$V_{\text{BE}(\text{sat})}$	_	_	1.5	V	$I_{\rm C} = 2.5 \text{ A}, I_{\rm B} = 0.5 \text{ A}^{*1}$
Turn on time	t <sub>on</sub>		_	0.5	μs	$I_C = 5 \text{ A}, I_{B1} = -I_{B2} = 1.0 \text{ A},$
Storage time	t <sub>stg</sub>	_	_	1.5	μs	V <sub>cc</sub> ≅ 150 V
Fall time	t <sub>f</sub>	_	0.3	0.5	μs	

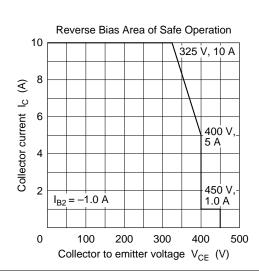
Note: 1. Pulse test.

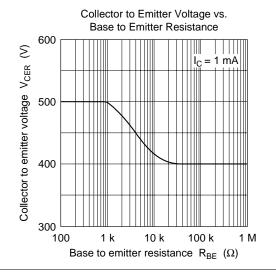


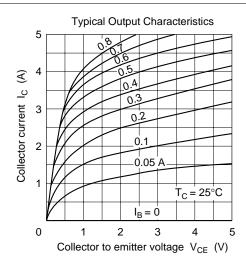


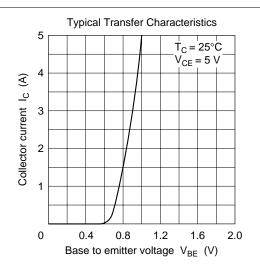


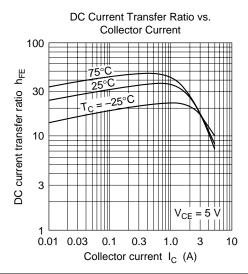


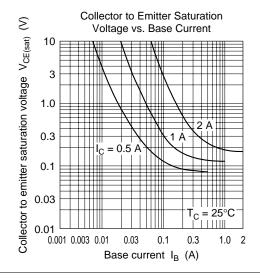


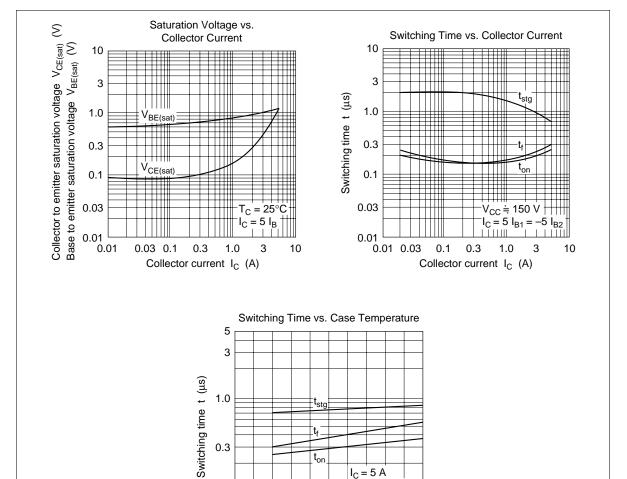












0.1

0.05 0

25

50

 $I_{B1} = -I_{B2} = 1 \text{ A}$   $R_L = 30 \Omega$ 

100

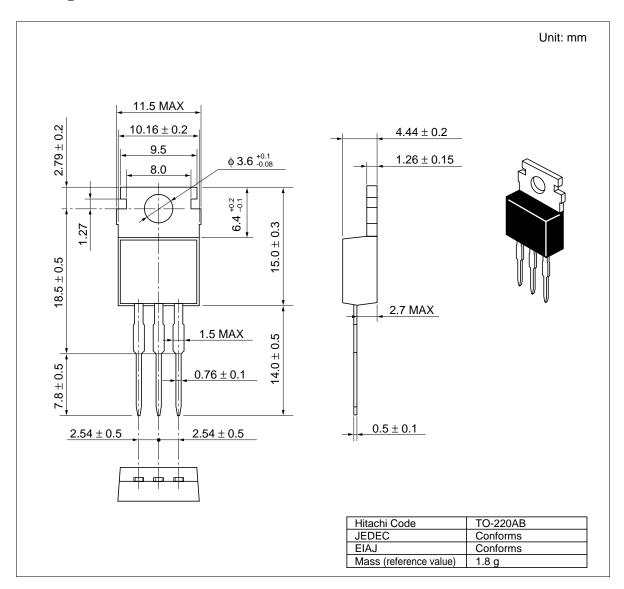
125

V<sub>CC</sub> = 150 V

75

Case temperature T<sub>C</sub> (°C)

### **Package Dimensions**



#### **Cautions**

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